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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-12-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMP100LC-8	8HZG*CWB008	A	BO2A	2014-12-04
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	MD valid for CP:SMB CLIP (SOD 6).			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	SHZG*CW008					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.809	mg	supplier	die	Silicon (Si)	7440-21-3		1.748	mg	966280	17837
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.025	mg	13820	255
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.01	mg	5528	102
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	3870	71
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1658	31
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	8845	163
Leadframe	Copper & its alloys	36.098	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.294	mg	977727	360143
Leadframe				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.035	mg	970	357
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	21303	7847
Soft solder	Solder	1.784	mg	JIG Table A	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.668	mg	934978	17020
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.027	mg	15135	276
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.089	mg	49888	908
Bonding wire	Other inorganic materials	18.33	mg	supplier	wire	Copper (Cu)	7440-50-8		18.33	mg	1000000	187041
encapsulation	Other Organic Materials	39.168	mg	JIG Table B	mold compound	Silica, vitreous	60676-86-0		29.768	mg	760008	303755
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		2.35	mg	59998	23980
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.314	mg	8017	3204
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.995	mg	101997	40765
encapsulation				supplier	mold compound	Metal hydroxide	na		0.783	mg	19991	7990
encapsulation				supplier	mold compound	Others	na		1.958	mg	49990	19980
connections coating	Solder	0.811	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276